

A

B

C

D

E

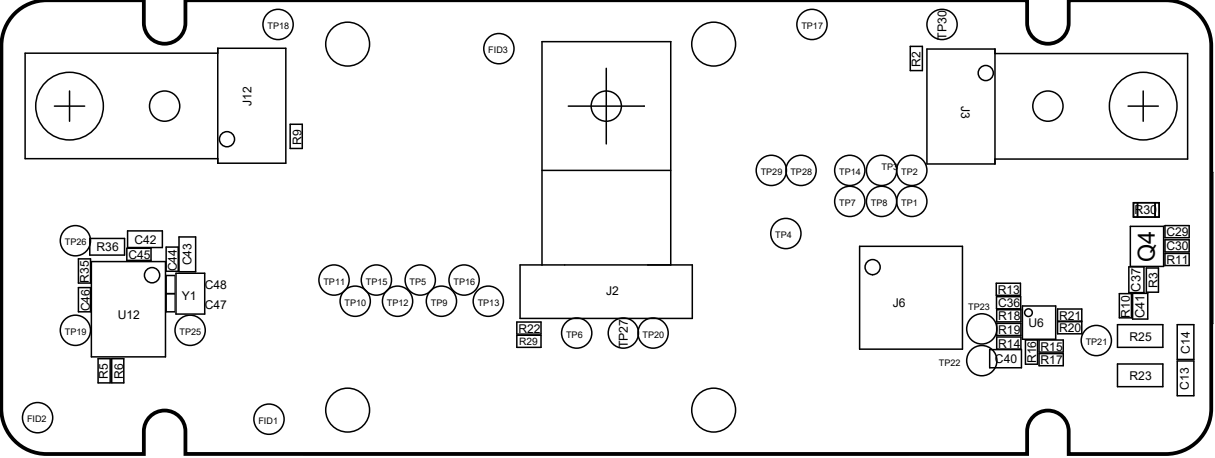
ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.  
Assembly shall conform with RoHS Directive 2011/65/EU.  
Components shall be placed according to the associated CPL and BOM documents.  
Lead-free SAC305 solder shall be used.  
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.  
BGA components shall be 100% checked with x-ray for solder bridges after reflow.  
Finished assemblies shall be removed from panel prior to delivery.

Notes:

- 1
- Note 1
- 2
- Note 2
- 3
- Note 3

View from Top side (Scale 2:1)



Title: <b>DM1095</b>	
Number: DXXXX	Revision: R0M0 E0
Date: 07/09/2021	Sheet: 1 of 2
Drawn by: David Malovrh	



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A

B

C

D

E

A

B

C

D

E

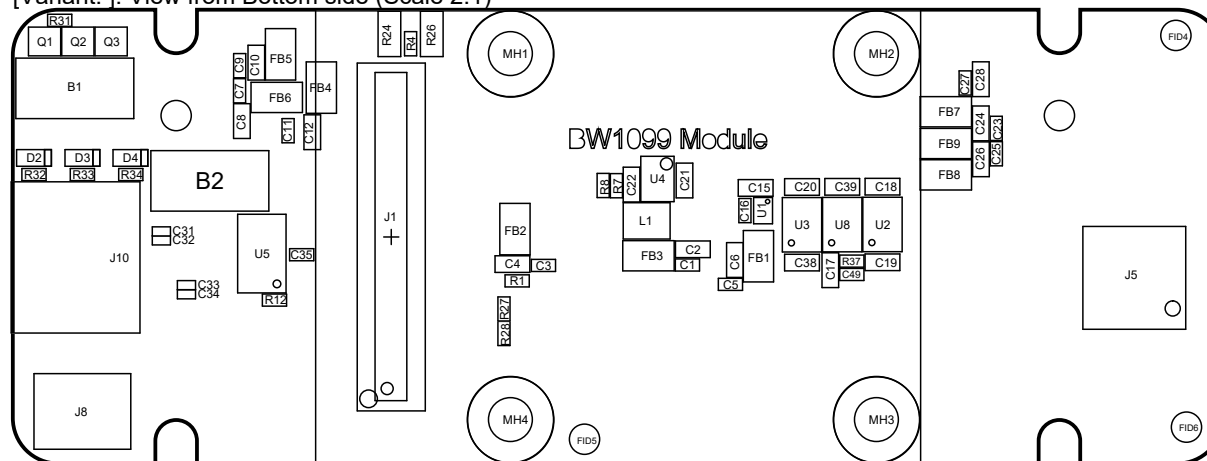
1

2

3

4

[Variant: ]: View from Bottom side (Scale 2:1)



Title: **DM1095**

Number: DXXXX

Revision: R0M0  
E0

Date: 07/09/2021

Sheet: 2 of 2

Drawn by: David Malovrh

**LUXonjs**

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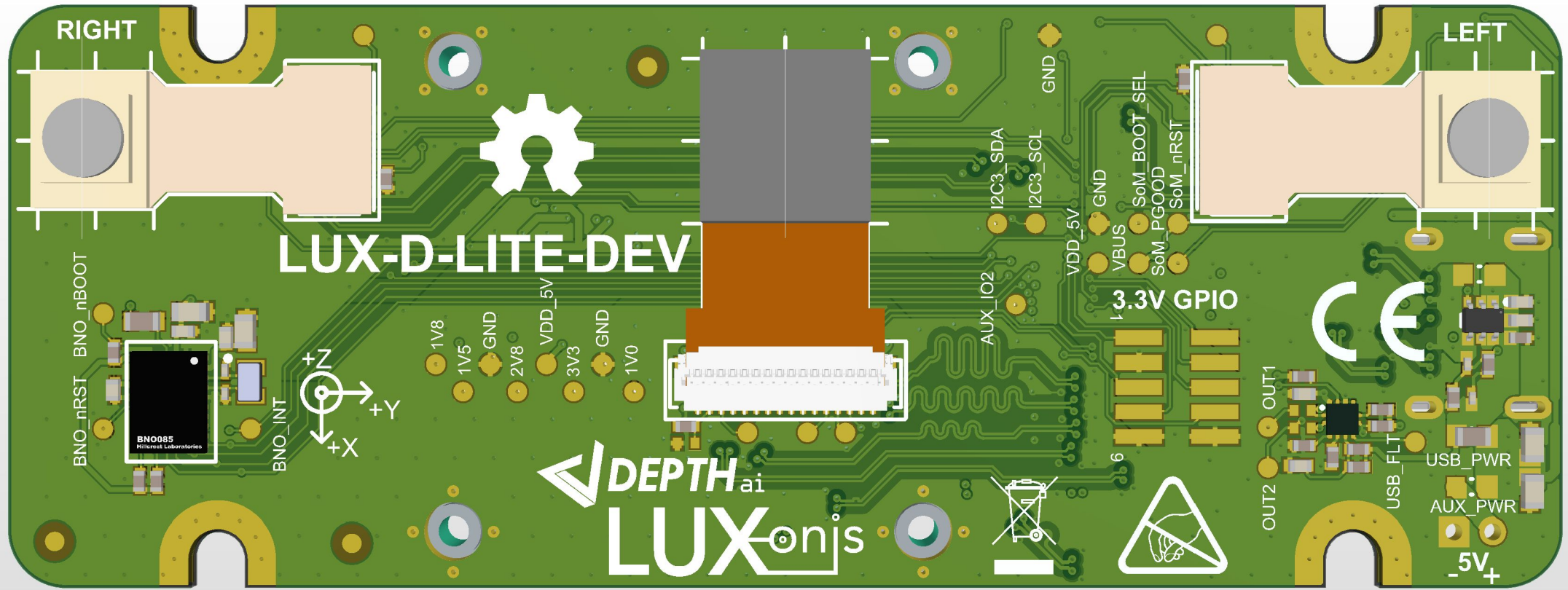
A

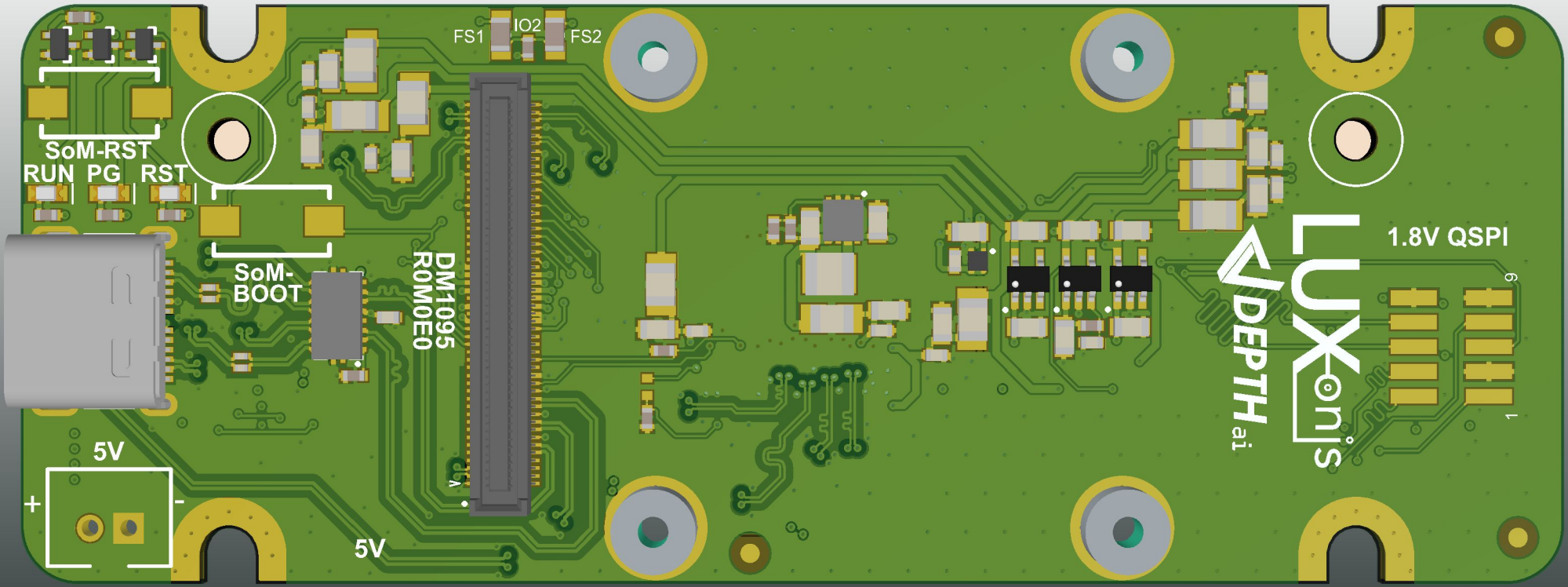
B

C

D

E





**LUXONIS**  
DEPTH ai

1.8V QSPI

DM1095  
R0M0E0

SoM-  
BOOT

SoM-RST  
RUN PG RST

5V

5V

FS1

IO2

FS2

6  
1